



DA3S101K0L

Silicon epitaxial planar type

For high speed switching circuits
 DA3J101K in SSMINI3 type package

■ Features

- Small reverse current IR
- Short reverse recovery time trr
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: 21

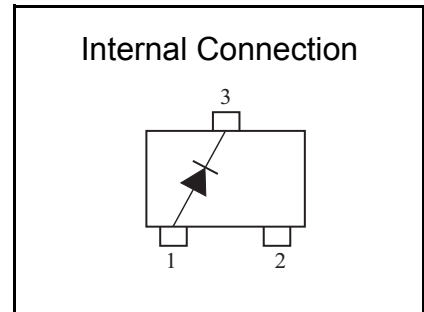
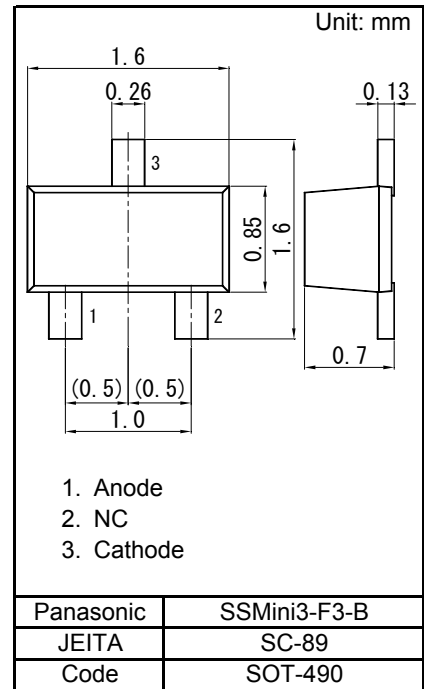
■ Packaging

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Reverse voltage	VR	80	V
Maximum peak reverse voltage	VRM	80	V
Forward current	IF	100	mA
Peak forward current	IFM	225	mA
Non-repetitive peak forward surge current *1	IFSM	500	mA
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Note) *1: t = 1 s



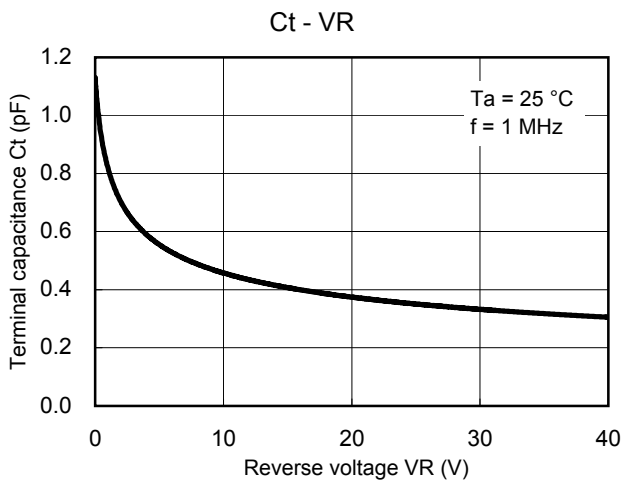
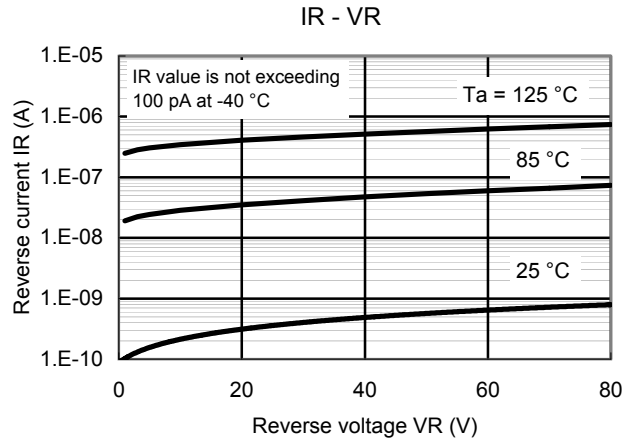
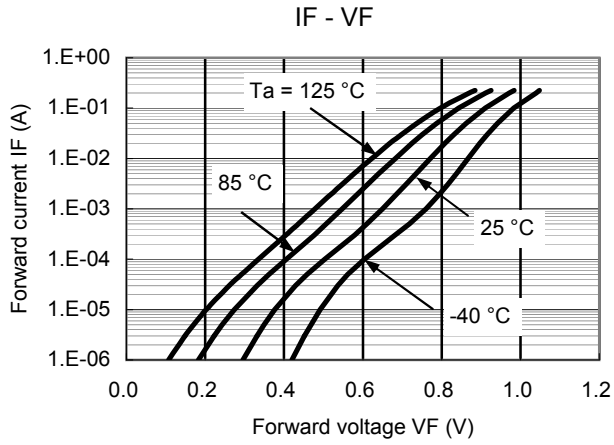
■ Electrical Characteristics $T_a = 25\text{ }^\circ\text{C} \pm 3\text{ }^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 100 mA		0.92	1.20	V
Reverse voltage	VR	IR = 100 μ A	80			V
Reverse current	IR	VR = 80 V			100	nA
Terminal capacitance	Ct	VR = 0 V, f = 1 MHz			1.2	pF
Reverse recovery time *1	t _{rr}	IF = 10 mA, VR = 6 V I _{rr} = 0.25 x IR			3	ns

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
 2. Absolute frequency of input and output is 100 MHz.
 3. *1: t_{rr} test circuit



Technical Data (reference)



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